Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP A6616 Router (JC496A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	10
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		8
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		12
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove film 1 from plastic panel 4.
2. Remove film 3 from plastic panel 4.
3. Remove plastic panel 4 from the chassis.
4. Remove plastic panel 5 from the chassis.
5. Remove mounting angle 6 from the chassis.
6. Unscrew the screws on part 7, and then remove part 7 from the chassis.
7. Unscrew the screws on front panel 8, and then remove front panel 8 from the chassis.
8. Unscrew the screws on drawing hand 10, and then remove drawing hand 10 from cover 9.
9. Unscrew the screws on power module 11, and then remove power module 11 from PCB 22.
10. Remove plastic panel 12 from the chassis.
11. Unscrew the screws on blank poe module panel 13, and then remove blank poe module panel 13 from the chassis.
12. Unscrew the screws on dustproof 14, and then remove dustproof 14 from the chassis.
13. Unscrew the screws on front panel 15, and then remove front panel 15 from the chassis.
14. Unscrew the screws on front panel 16, and then remove front panel 16 from the chassis.
15. Unscrew the screws on blank filler panel 17, and then remove blank filler panel 17 from the chassis.
16. Unscrew the screws on fan frame 18, and then remove fan frame 18 from the chassis.
17. Unscrew the screws on back cover 20, and then remove back cover 20.
18. Unscrew the screws on rib 19, and then remove rib 19 from the chassis.
19. Unscrew the screws on PCB 21, and then remove PCB 21.
20. Unscrew the screws on PCB 22, and then remove PCB 22.
21. Unscrew the screws on wire channel 6-2, and then remove wire channel 6-2 from mounting angle 6-1.
22. Unscrew the screws on wire channel 6-3, and then remove wire channel 6-3 from mounting angle 6-1.
23. Remove shielding finger 8-5 from front panel 8-1.
24. Unscrew the screws on PCB 8-3, and then remove PCB 8-3 from front panel 8-1.

25. Remove film 8-4 from front panel 8-1.
26. Unscrew the screws on PCB 8-2, and then remove PCB 8-2 from front panel 8-1.
27. Remove film 15-2 from front panel 15-7.
28. Remove film 15-3 from front panel 15-1.
29. Remove shielding finger 15-4 from front panel 15-1.
30. Unscrew the screws on PCB 15-5, and then remove PCB 15-5 from front panel 15-1.
31. Unscrew the screws on PCB 15-6, and then remove PCB 15-6 from front panel 15-1.
32. Unscrew the screws on PCB 17-2, and then remove PCB 17-2.
33. Unscrew the screws on PCB 17-3, and then remove PCB 17-3.
34. Unscrew the screws on bracket 17-4, and then remove bracket 17-4.
35. Unscrew the screws on PCB 17-1, and then remove PCB 17-1.
36. Unscrew the screws on PCB 18-2, and then remove PCB 18-2.
37. Unscrew the screws on fan 18-3, and then remove fan 18-3 from fan frame 18-1.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

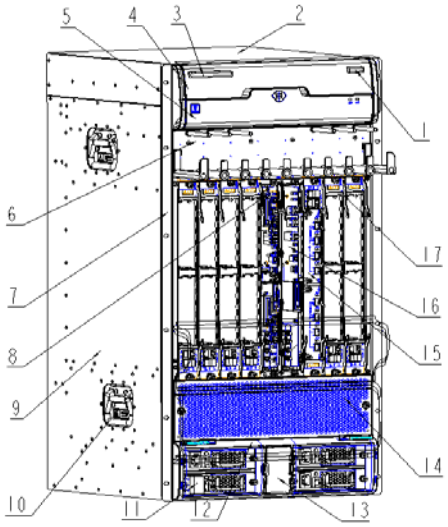

Figure 1 Treatments to the product(front view)

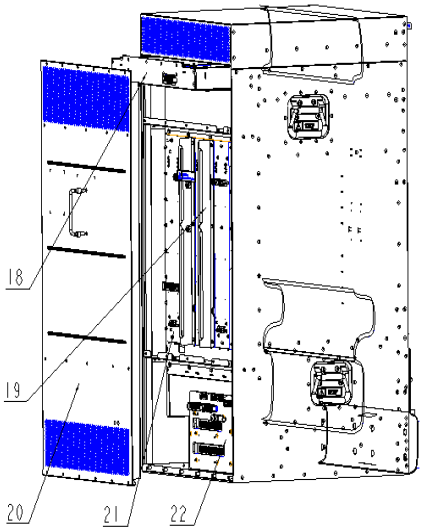

Figure 2 Treatments to the product(rear view)

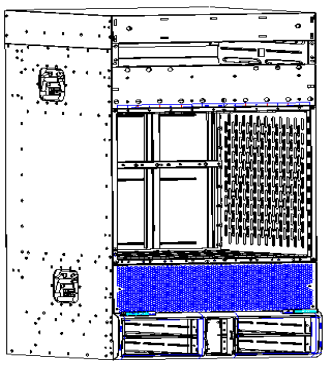

Figure 3 Part 2

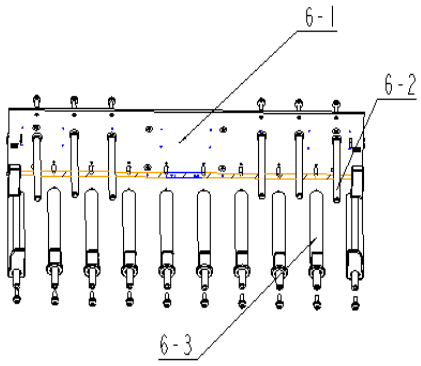

Figure 4 Treatments to mounting angle 6

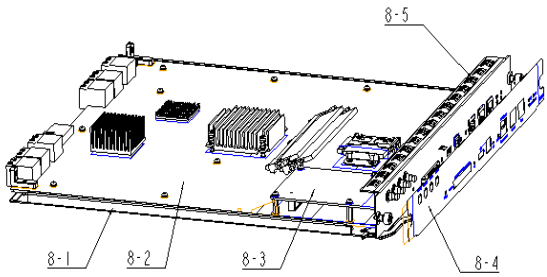

Figure 5 Treatments to front panel 8

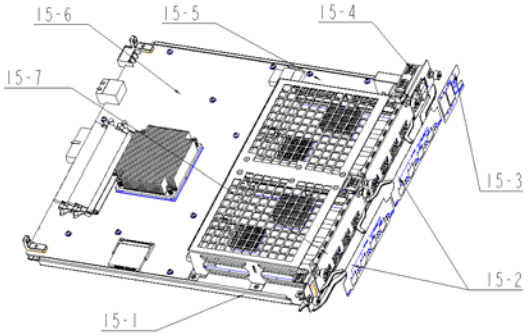

Figure 6 Treatments to front panel 15

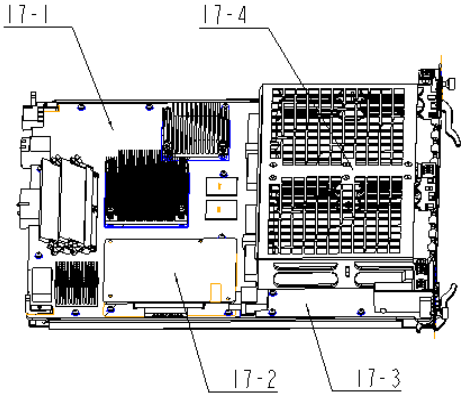

Figure 7 Treatments to front panel 17

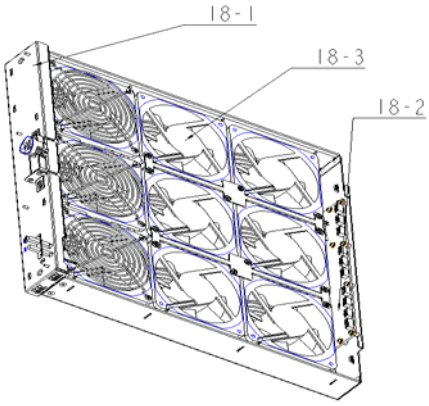

Figure 8 Treatments to fan frame 18

PSG instructions for this template are available at EL-MF877-01